English

ACCRETECH



COMPANY PROFILE





The location information listed in this brochure is current as of the time of publication. Please check the QR code or our official website for the latest information.

ACCRETECH Location information

https://www.accretech.com

- We reserve the right to change the contents of this catalog, including product specifications, without notice when products are updated.
- Content is based on information available at the time of publication.

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ACCRETECH TOKYO SEIMITSU

CORPORATE MOTTO

WIN-WIN RELATIONSHIPS CREATE THE WORLD'S No.1 PRODUCTS

Our corporate brand " ACCRETECH " was created from the words "Accrete," which means Grow Together, and "Technology."
In a single word, the brand name represents our corporate philosophy: growing together with partners and customers
by way of creating the world's best products by gathering the finest technology, intelligence, and information.



Message from the Management

Since our foundation in 1949, the Tokyo Seimitsu Group has consistently pursued "customer satisfaction" and has focused on product development and customer support. Thanks to everyone's support, we have grown into a global company with group companies operating in 18 countries and regions around the world.
The purpose (raison d'être) of the Tokyo Seimitsu Group is "Gaging the future with Metrology, Creating the future with Semiconductors." Based on this purpose, the Tokyo Seimitsu Group aims to build a "future full of dreams" by growing together with our partners and customers, and by collaborating technology, knowledge, and information to create the world's No.1 products.
Society is rapidly changing, with globalization, the addressing of environmental issues, and the advancement of digitalization progressing. The Tokyo Seimitsu Group promptly responds to these changes and continues to support customers' manufacturing innovation by refining the technologies cultivated since its foundation and leveraging its strengths as a manufacturer of semiconductor manufacturing equipment that possesses the power to achieve technological innovation and measurement technologies.
The Tokyo Seimitsu Group, based on the action guidelines of "Health and Safety", "Quality", "Environment and Energy Conservation", and "Integrated Efforts of All Employees", will continue to develop and supply excellent semiconductor manufacturing equipment and precision measuring instruments to satisfy our customers and contribute to society.
We greatly appreciate your continued warm understanding and support.



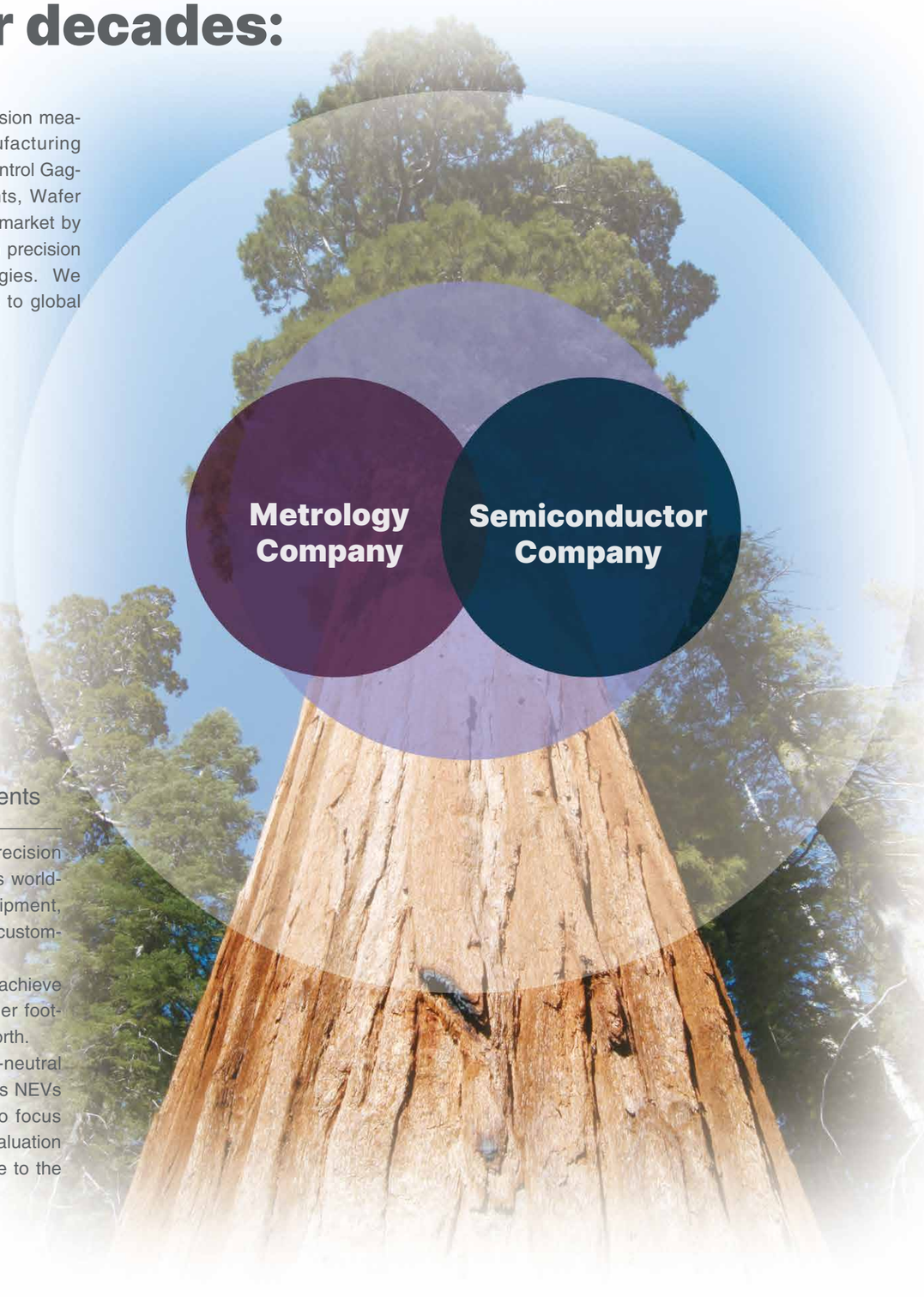
President and CEO
Ryuichi Kimura

*What our symbol mark expresses:
The spinning golden orb represents a dynamic mixture of resources (people, goods, funds, and information) concentrated from all over the world. By condensing those powers, we will introduce powerful, state-of-art products into the market with clear targets. This is expressed by the jet streams shooting out at high speed from the center of the orb.

Our origin and future

Tokyo Seimitsu continues to introduce “World No.1 Products” to the global market respecting the core - technology we’ve cultivated for decades:

Tokyo Seimitsu, as a manufacturer of precision measuring devices and semiconductor manufacturing equipment, has been supplying Machine Control Gages, Surface Texture Measuring Instruments, Wafer Probing Machines, and more to the global market by applying our key technologies such as high precision micro positioning and measuring technologies. We will continue to introduce superb products to global market going forward.



High Precision Measuring Instruments

Metrology Company has supplied High Precision Measuring Instruments to various industries worldwide such as automobile, heavy duty equipment, aircraft, etc. and has been highly valued by customers all over the world.
We continue our product developments to achieve enhanced environmental durability, a smaller footprint, and fully automatic operation and so forth.
In addition, for the realization of a carbon-neutral society, in order to meet new needs such as NEVs or renewable energy market, etc., we also focus on the development of the performance evaluation system for secondary battery and contribute to the creation of the future society.

Semiconductor Production Equipments

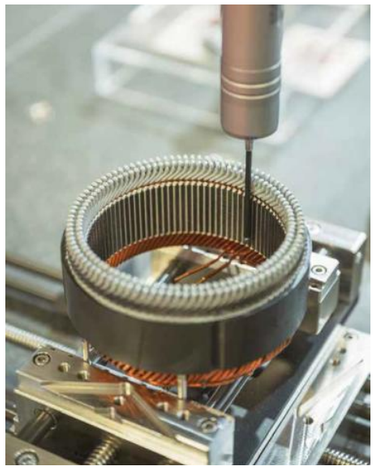
Our Semiconductor Company holds the largest global market share, specifically in the conventional fields of wafer manufacturing, test, and back-end processing. In addition, we have also been active in the fields of CMP (Chemical Mechanical Planarizers) and Polish Grinders to fulfill our customers’ needs to build the optimum production systems.

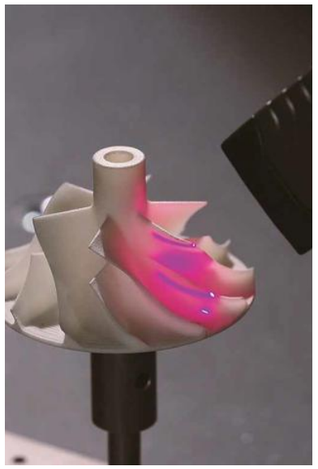
Multipurpose Measuring Instruments

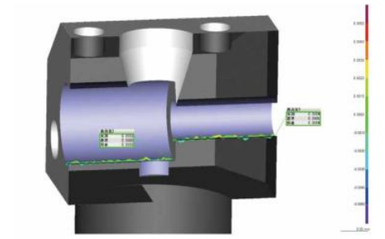
Coordinate Measuring Machines

**Tokyo Seimitsu developed Japan's first coordinate measuring machine.
To meet all kinds of needs, we offer a diverse lineup that combines
our own products with products from Carl Zeiss.**

A coordinate measuring machine is used for accurate three-dimensional measurements of the dimensions and shapes of objects.
In 1969, Tokyo Seimitsu developed Japan's first coordinate measuring machine. Since then, we have been making tireless efforts to accommodate customer needs, establishing a solid position as a market leader in Japan. Our diverse lineup includes the XYZAX AXCEL Series featuring high accuracy, high speed, and high environmental resistance, as well as products from our long-time partner, Carl Zeiss. These products help customers solve the various measurement challenges they face.









XYZAX Series

＜ Multipurpose type CNC ＞



XYZAX AXCEL RDS/PH
A global standard 3D coordinate measuring machine featuring high accuracy, high speed and high environmental resistance and supporting a variety of probe systems



XYZAX mju NEX
Hybrid guideway technology provides stable measurement accuracy and energy savings.

＜ Manually operated type ＞



XYZAX SVF NEX
Easy-to-operate manual coordinate measuring machine

Carl Zeiss Series （CNC）

＜ Ultra-high precision type ＞



ZEISS XENOS
Coordinate measuring machines are stepping into a new realm
World's highest-class* maximum permissible error of length measurement
$E_{0,MPE}$ = 0.2+L/1000 µm
* Based on our research. When compared to contact-type coordinate measuring machines supporting a measurement range of a similar size



ZEISS PRISMO® Series
Product lineup consisting of "ultra" for ultra-high-accuracy measurement, "verity" for high accuracy measurement, and "fortis" for on-site measurement in addition to standard models

＜ Type for on-site measurement ＞



ZEISS DuraMax® Series
A slim and space-saving coordinate measuring machine for on-site measurement

＜ Multipurpose high-precision type＞





ZEISS CONTURA®
A single unit is capable of performing all types of contact and non-contact measurement.

＜ Multipurpose type＞





ZEISS SPECTRUM Series
Optimal solution meets your needs with selectable specifications × innovative technology.

＜ Extra-large type＞

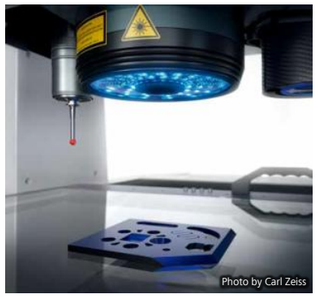




ZEISS MMZ Series
An extra-large coordinate measuring machine featuring both an extremely large measurement range and high accuracy

＜ Image / multi-sensor type＞





ZEISS O-INSPECT
A multi-sensor measuring instrument equipped with both contact and optical measuring technologies

Multipurpose Measuring Instruments

X-ray CT systems

The surface and the internal parts, in a single measurement.
We provide an “X-ray CT system for measurement” that not only observes the interior of the workpiece, but also performs high-precision, non-destructive measurements.

An X-ray CT system visualizes the internal structure of an object using cross-sectional or three-dimensional images obtained with X-rays. Particularly, we provide an “X-ray CT system for measurement” that not only visualizes the internal structure of an object but also enables highly accurate evaluation of dimensions, shapes, and geometrical tolerances.



ZEISS METROTOM
Next-generation X-ray CT system for measurement with wide range, high precision, and high resolution



Insightcom® 160
An X-ray CT system for measurement that combines ease of use with high reliability



Multipurpose Measuring Instruments

Optical shaft measuring systems

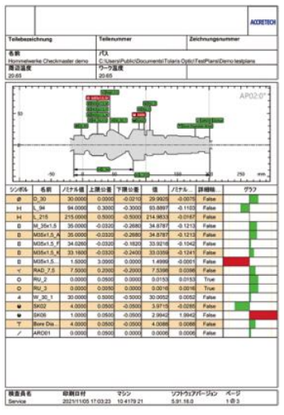
The measurements and shape of the shaft or rotating parts are measured in an overwhelmingly short time.
In our lineup, we can handle inspection and automation during production processes, so we can contribute to increased productivity at your company.

An optical shaft measuring system illuminates the workpiece with light and captures its shadow with an image sensor to evaluate the dimensional tolerance and geometrical tolerance. Tokyo Seimitsu’s Shaftcom C Series includes a contact-type probe-equipped model capable of measuring non-through holes and grooves that are difficult to handle in optical measurement. Shaftcom C can measure various evaluation items of shafts and rotating parts in a short time.



Shaftcom C
The dimensional tolerance and geometrical tolerance of a shaft-shaped workpiece can be evaluated in a short time.



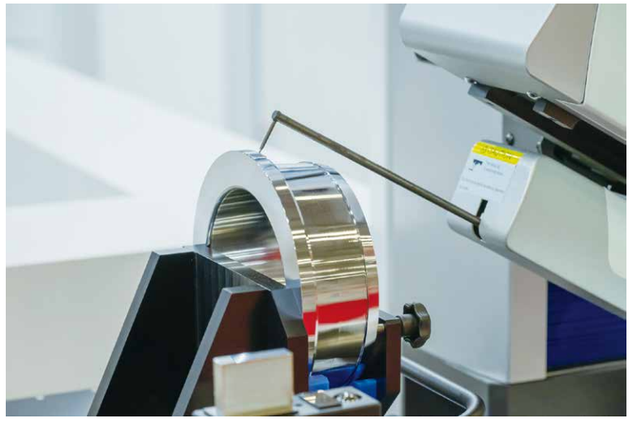


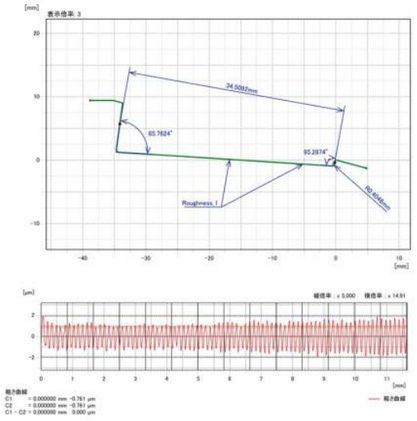
Multipurpose Measuring Instruments

Surface Texture and Contour Measuring Instruments

We provide high performance, easy-to-use systems from highly efficient hybrid types that can measure the surface texture and the contour in one trace, to portable types that can be used even on the production site.

A surface texture and contour measuring instrument quantifies and evaluates the surface texture and contour with high precision.
In 1957, Tokyo Seimitsu developed Japan’s first LVDT type electric micrometer. Turning the knowledge into detector technology, we launched the surface texture measuring instrument Delta SURFCOM in 1962. Since then, we have expanded our product portfolio from surface texture measuring instruments to contour measuring instruments and then to hybrid models and non-contact measuring sensors, extensively contributing to customers’ manufacturing as the market leader in Japan.





＜ Ultra-high precision / hybrid ＞



SURFCOM CREST
This integrated surface texture and contour measuring instrument boasts the world’s highest level of precision*.

* Based on our research. When compared to surface texture and contour measuring instruments supporting a Z-axis measurement range of a similar size that can measure surface texture and contour simultaneously

＜ Hybrid ＞



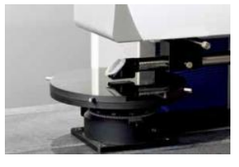
SURFCOM NEX (DX2/SD2)
The latest global standard model capable of efficiently measuring all kinds of workpieces in a short time across a wide range of temperatures

＜ Portable / surface texture ＞



HANDYSURF+
A portable surface texture measuring instrument for global use responding to diverse needs

＜ Non-contact displacement detector ＞



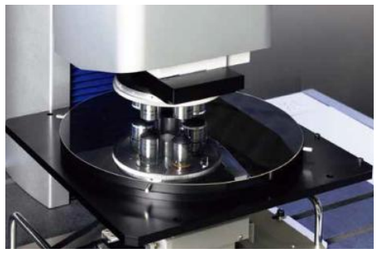
ACCHROS
A non-contact displacement detector newly developed for surface texture and waviness profile measurement that utilizes the principle of color confocal

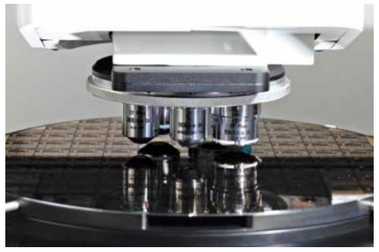
Multipurpose Measuring Instruments

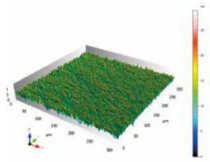
Non-contact Surface Texture and Contour Measuring Instruments

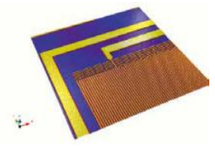
From sub-nanometer roughness through millimeter shape in 3D.
Tokyo Seimitsu's extensive lineup of white light interferometry microscopes meets the needs for non-contact surface texture and contour evaluations.

A non-contact surface texture and contour measuring instrument enables non-contact 3D visualization of surface texture and fine shapes. A single instrument can evaluate sub-nanometer surface texture, fine 3D shapes, and millimeter shapes including degrees of wear and steep inclines. Various models of different sizes are available, each designed for a specific workpiece size and shape, contributing to quality assurance in advanced manufacturing processes.

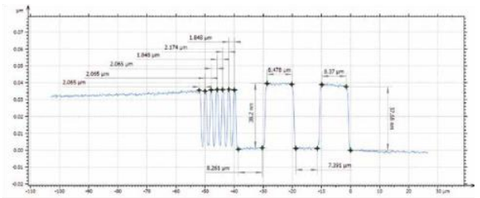














Opt-scope



Opt-scope NEX



Opt-scope Rex

Opt-scope Series

A 3D white light interferometer microscope that can evaluate widely from sub-nanometer roughness through millimeter shape

Multipurpose Measuring Instruments

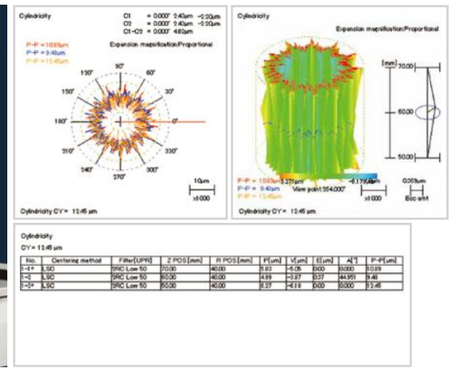
Roundness and Cylindrical Profile Measuring Instruments

We respond to a variety of needs with our lineup including both rotating table types that enable high precision measurement of cylindrical workpieces, and rotating type detectors that handle eccentric or heavy workpieces.

A roundness and cylindrical profile measuring instrument precisely measures the shape accuracy of a circular or cylindrical shape. Tokyo Seimitsu developed Japan's first high pressure flow-type air micrometer (in 1953) and Japan's first LVDT type electric micrometer (in 1957). Turning the knowledge into air bearing and detector technologies, we launched the roundness measuring machine ETR-1A in 1967. Today, our diverse lineup includes a high-end model featuring world-class* ultra-high precision, a multi-function model with roundness, diameter, and surface texture measurement capabilities, and a detector-rotating type model capable of measuring engine parts and other large workpieces, thereby meeting all kinds of customer needs.







< Ultra-high precision >



RONDCOM CREST

The flagship model of the table-rotating type that offers world-class rotation accuracy* in both radial and axial directions

* Based on our research. When compared to roundness and cylindrical profile measuring instruments supporting a measurement range of a similar size

< Multi-function >



RONDCOM NEX (DX2/SD2)

The latest global standard model that enables effortless measurement of all kinds of workpieces, thanks to a rich lineup of features and outstanding labor-saving options

< Detector-rotating type >



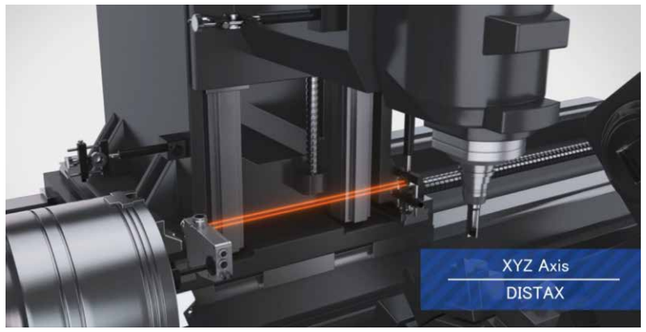
RONDCOM 76A

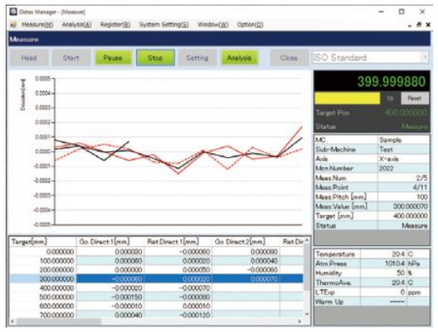
The flagship model of the detector-rotating type that can measure large workpieces or heavy workpieces in a short time

Multipurpose Measuring Instruments

Laser Interferometers

Capable of measuring linear displacement, yawing and pitching, rotation angles, overshoot during vibration or stoppage, and speed fluctuations.
A length-measuring instrument suitable for a wide range of applications, including precision inspection of machine tools

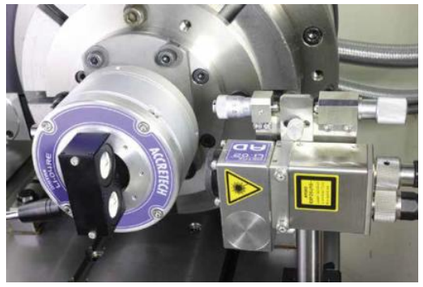






DISTAX

A high-precision, easy-to-use laser interferometer with optical fiber and machine-tool inspection system



Multipurpose Measuring Instruments

Non-contact Displacement Sensors

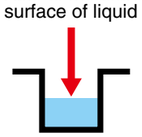
A flexible sensor that can be installed anywhere and is equipped with high environmental resistance enabling use in harsh environments.



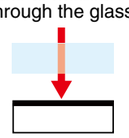
Opt-measure

A white light interferometry-based length measuring system.
The system enables highly precise, highly sensitive measurement and can adapt to changes in the ambient temperature.

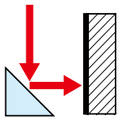
Able to measure surface of liquid



Able to measure through the glass



Able to measure by bending the optical path



Able to continue measurement even the light is shut out



Charge/Discharge Testing Systems

Battery Test System

Charge/discharge testing systems are measuring systems indispensable for charge and discharge cycle tests conducted in research and development of rechargeable batteries and capacitors as well as in quality assurance (sampling and reliability tests). These systems allow a variety of tests, including performance and durability tests, to be performed automatically on rechargeable batteries and capacitors for a broad range of products that have recently come into increasing use, from consumer mobile devices to electric vehicles.

Tokyo Seimitsu provides “charge/discharge testing systems,” “battery jigs,” “battery evaluation contract service,” and “maintenance service.”

Charge/Discharge Testing Systems

These systems are used to perform performance tests optimal for research, development, and quality control of cell, module, and pack rechargeable batteries and capacitors.



Energy-Sharing Charge/ Discharge Testing Systems



Cells



Module



Packs

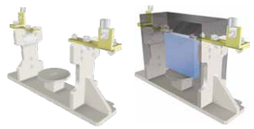






Battery jigs

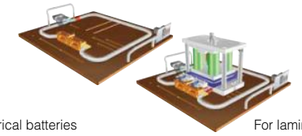
The Company provides battery evaluation jigs that realize “stable measurement,” “equipment safety,” “human safety,” and “labor saving” in cycle tests and characteristic tests conducted when developing rechargeable batteries and capacitors.
The jig is designed and created as appropriate for the battery shape, including rectangular, cylindrical, and laminated batteries.



For rectangular battery



For cylindrical batteries



For laminated batteries

Battery evaluation contract service

Building on the power supply technology that we have amassed over the years, we, as the pioneer in charge/discharge testing systems, provide a battery evaluation contract service that meets diverse customer needs.

「Four Strengths」

①Technical capabilities and ability to respond to customer needs as a manufacturer that develops and sells charge/discharge testing systems

②Track record of delivering more than 2,000 units to 100 companies and customers (testing know-how)

③Abundant professional staff and a team dedicated to testing + a team dedicated to battery evaluation and quality

④Strong relationships with battery measuring equipment manufacturers, analysis companies, and certification organizations

&

「New developments」

Provision of our own dedicated battery delivery service that realizes safety inspections during transportation

Provision of battery disposal service based on SDS (Safety Data Sheet) information

Providing a remote function that enables even distant customers to check data under evaluation in real time



Battery evaluation center

Maintenance service

Tokyo Seimitsu provides a rich line of services including the field adjustment, relocation, version upgrade, and repair of charge/discharge testing systems.

Automatic Measuring Instruments

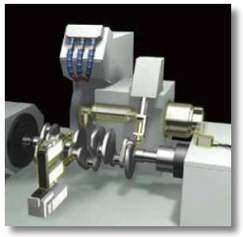
In-Line Measuring Systems

Unequaled Reliability, Uptime and Quality

SBS automatic balance system



Measuring system for grinding machines



SBS AE sensor system



Crankshaft journal and pin outer diameter measuring and marking machine

Measures journal and pin diameters with dedicated triple heads and marks prescribed positions.



Finished product

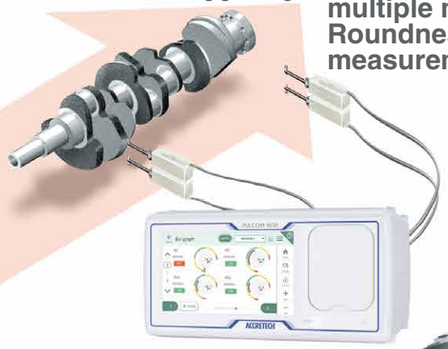
Integrated auto-inspection machines



Finished product

Pin / Journal finishing grinding

Outer diameter multiple measurement + Roundness measurement



Rear / Front finishing grinding

Journal semi-finishing grinding

Outer diameter measurement

Outer diameter measurement

Reference plane cutting

Crankshaft process line



Cylinder block process line



Front / Rear plane cutting/drilling

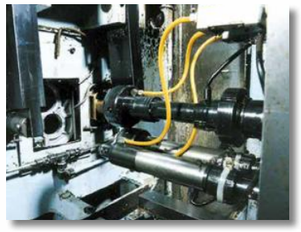
Cylinder liner Machining after boring



Inner diameter measurement

Cylinder block measuring and marking machine

Automated machine that measures bore diameters for crankshaft, as well as crankshaft bore coaxiality, and marks a prescribed position.



Internal diameter measuring system for lathe post-process

Chips





Measuring system for machining center

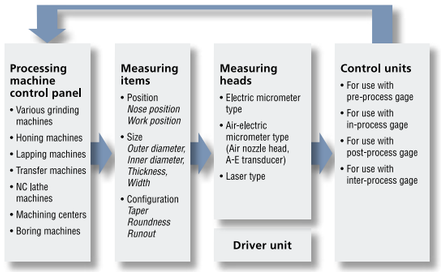
Tokyo Seimitsu became a supplier of in-line measuring instruments when Japanese automobile industries began to thrive in 1960s. From that point on, the automobile production lines have been required to operate 24 hours a day, 7 days a week, 365 days a year to produce high quality products on time. As a supplier, we have always been responding to customers' needs, for instance, by developing real time control using in-process gauge, feedback control using post-process gauge, and the integration of the two.

Furthermore, we have earned superb customer reputations as a result of our total support package including shorter turnaround, high liability, and best application capabilities; not to mention the excellent local support network that we have built to assist customers on a daily basis.

Our built-up experiences and accomplishments as a supplier of in-line measuring instruments became the strong backbone of the entire Tokyo Seimitsu group, including the semiconductor equipment sector.

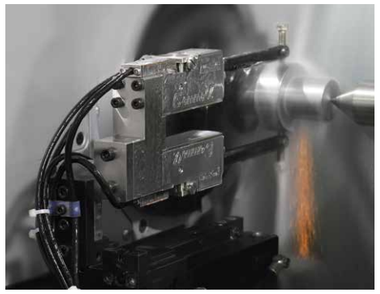
Automatic Measuring Instruments

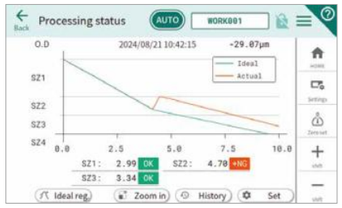
Machine Control Gages

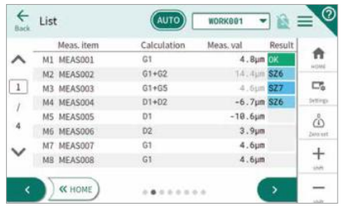


Powerful lineup : high-precision measurement and machine control in real time

Machine Control Gauge PULCOM utilizes the measured data collected either, before, during, or after the process to control the production machine in real time. PULCOM is mainly recognized for its high precision, which is considered second to none. PULCOM enables 0.1 µm precision measuring, which surpasses any previously introduced systems, and thus is capable of assisting our customers with their on-going pursuit for accurate machining capabilities.PULCOM is also waterproof and is suitable for any production environments so that it can be widely utilized for in-line high speed measurements and device controls.Along with PULCOM, we also customize various other auto-measuring, marking, and sorting devices that have been well accepted by global markets.







Measuring Heads

•Improved stability (Outstanding measuring head in temperature fluctuation)
•Compact size and small space.



Control Unit for Machine Control Gauge



Control unit for in-process and post-process measurement

PULCOM W10

- Substantial increase in measurement flexibility
- Support of diverse on-site network environments
- All-in-one solution featuring all high-end models of the PULCOM V Series
- Intuitive, stress-free operations

ACCRETECH Accretech SBS Products SBS DYNAMIC BALANCE SYSTEM



SBS in-process module-type controller

SB-6500

- Combines the three functions frequently used for grinders - sizing gauge, auto balancer, and AE sensor - into a single system.



SBS automatic balance system

- Extremely robust and speedy
- Maintaining or improving machining quality



SBS AE sensor system

- High analytical performance and operability
- Suitable for machining monitoring and reducing cycle time

Automatic Measuring Instruments

Sensors, Analyzers and Display Units

High accuracy and proven reliability in a compact format

Tokyo Seimitsu developed a large selection of sensors according to the measurement principles in order to fit any purposes fund in the various production measuring scenes. These well-established sensors have earned high reviews over the years, as they are easy to use and observe during the line measurements, are capable of high-speed response suitable for machine built-in, and guarantee high accuracy crucial for liable inspection results. We are actively engaged in the development of various types of non-contact sensors and more to fulfill future demands.

Air Micrometers





DELTAIR 22H

High Precision Digital Length Measurement Instruments

PHA Series



PC connection type Inspection system

USB connection

- The data is captured by PC
- USB-Bus powered system
- Multi-gage system

Various lineup

- LVDT-USB : Compact measuring head, electric micrometers
- PHA-USB : High precision, wide range of measurement, optics scale gage
- Air micro USB : Converting the minute dimensional change detected by air nozzles to electric signal



Aluminum High-Speed Cutting Process Monitoring Device

ATC Runout Detection System RD10

•Detect tool for run-out to prevent manufacturing error.



Contact Type Wafer Thickness Measuring Systems

WT-425 Series



Inner-Diameter Measuring Head for ATC Wireless Bore Gauge

BG-300

- Bore gauge for ATC using wireless communication





Semiconductor Production Equipment

Wafer Probing Machines

Responding to the progress of device technologies and measurement needs of the next generation, Tokyo Seimitsu continues to lead the Semiconductor industry by offering solutions equipped with state-of-the-art intelligent features.

Next-generation ultra-high-performance probing machine

AP3000/AP3000e is a next-generation ultra-high-performance probing machine designed to achieve high precision, high throughput (index move, wafer handling, and wafer alignment), low vibration and low noise. Anti-Virus/Anti-Malware software is installed as standard software on the machine.
The functions and operability of AP3000/AP3000e are inherited from previous models, and it maintains compatibility of recipe and map data. It is very user friendly with the safety and security in mind.



AP3000 / AP3000e

This high-performance probing machine achieves high precision, high throughput (index move, wafer handling, and wafer alignment), low vibration, and low noise at a high level.
The model comes standard with anti-virus and anti-malware software.



AP3000W / AP3000eW

While retaining the functions of AP3000/AP3000e, this machine can be equipped with interfaces for large probe cards and large test heads. Inheriting the functions and operability of the previous models, the machine maintains compatibility of recipe and map data and ensures safe, secure, and easy operation.



FP3000W

The thin wafer mounted on the dicing frame, diced wafer, and CSP substrate are automatically transferred by frame and gone through the probing test.

As the top manufacturer of wafer manufacturing and device test systems, Tokyo Seimitsu has always driven proactive technological development. By integrating advanced expertise accumulated over many years of operation with the latest technologies, the Company offers another range of advanced products to customers.



AltaProv

This probing machine adopts Tokyo Seimitsu's unique contact system (vacuum suction) and pogo pins and enables full wafer testing on a single touchdown, helping to cut test costs.
The dedicated XY stage enables simultaneous measurement on 12 stages.



AP3000-i5

Connected test heads can be installed side by side, leading to a minimal footprint. This probing machine can distribute wafers in the FOUP to multiple testers, minimizing the lot processing time for wafers.

Semiconductor Production Equipment

Wafer Probing Machines

Prober variation satisfying various device demands – UF Series

The UF series probing machines were developed by combining the latest technologies of Tokyo Seimitsu. Exhibiting high accuracy, high efficiency, and high functionality, it further offers the full automation, self-diagnostic function, use of GUI, high operation performance and stability.



UF2000

- High precision 200 mm Wafer Probing Machine.
  Probing machine with ±1.5 µm precision, high rigidity and high throughput.
  This machine demonstrates its performance through utilization of a new processor and the quality of its new loader.



FP2000

- Machine ready for tape frame transportation.



UF200R

- Super high-rigid machine for memory.



UF190R

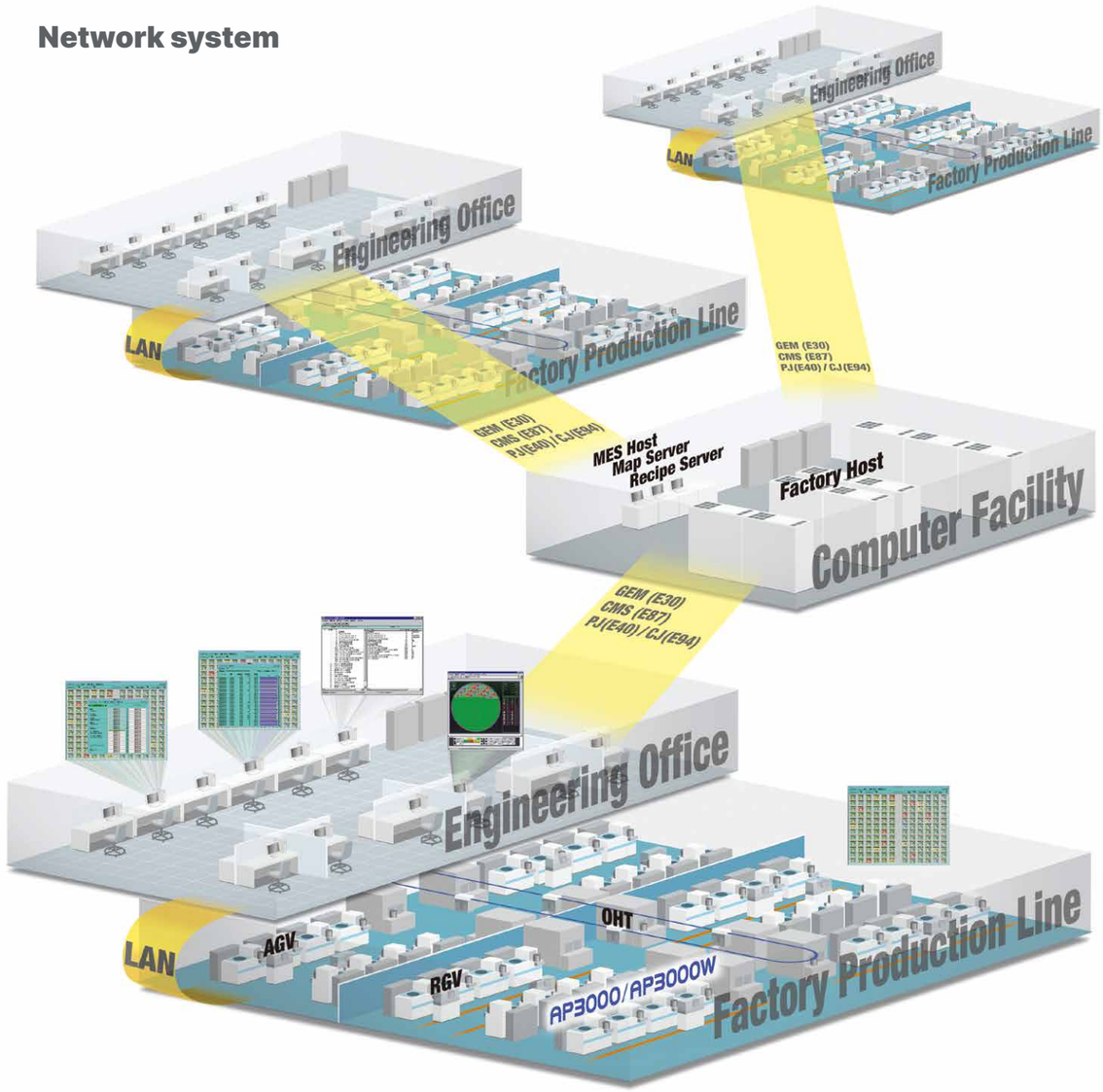
- High-speed machine for bipolar.

ACCRETECH network useful for test process quality and data management, test result analysis and automation at customer sites.

System Integration

The ACRRETECH Probers take initiative in the factory automation process by employing the SEMI standards of GEM (E30), CMS (E87), PJ (E40), or CJ (E94), combined with our original networks Vega-Net, Light-Veganet, and Vega-Planet. The UF series are equipped with the next-generation remote terminal function which provide the e-Maintenance/e-Diagnostic.

Network system



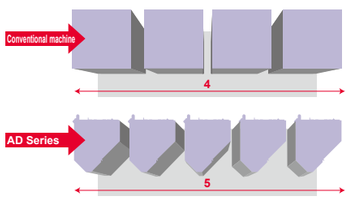
Semiconductor Production Equipment

Fully Automatic Dicing Machines

Designed to reduce the footprint and built on the concept of high maintainability, these machines offer an optimal dicing environment.

Tokyo Seimitsu's fully automatic dicing machines feature high throughput and high processing quality, ensuring excellent CoO (Cost of Ownership). The unique diagonal layout mechanism is adopted to make effective use of floor space and maximize production efficiency. The combination of a highly rigid gate-type structure and a opposing twin spindle design allows these machines to deliver high productivity with two spindles while realizing small footprint.

Downsizing was achieved in both AD Series in comparison with the conventional equipment.





TWIN Dicing concept with the face-to-face twin-spindles



AD3000T-PLUS

- Fully automatic dicer compliant with 300 mm work that is equipped with the face-to-face twin-spindles.
- High power spindle as a standard feature.
- A rich variety of option settings
  The intermediate dressing function, built-in UV irradiation system, and ionizer and other optional units are made smaller and adopt internal optimal designs, making it possible to build the main optional units into the machine.



AD3000T-HC PLUS

- Fully automatic dicer with opposing twin spindles capable of handling 300-mm-wide workpieces.
- Automatic WH/FH switchover
  Wafer handling (WH) and frame handling (FH) can be automatically switched simply by setting a recipe.
  This helps reduce the person-hours for step switchover and prevent an operational error.



AD2000T/S

- Fully automatic dicer compliant with 200 mm work that is equipped with the face-to-face twin-spindles / single spindle.
- High power spindle as a standard feature.



AD3000TW

- A model with face-to-face twin spindles for large packages
- Supports dicing of larger packaging substrates, including Fan-out WLPs.
- Supports dicing of multiple packaging substrates by selecting a special dicing frame or square table, contributing to improved productivity and cost reductions.

Semiconductor Production Equipment

Semi-Automatic Dicing Machines

User-friendly operations ensure high processing quality.

Based on its quantitative dicing know-how amassed over the years, Tokyo Seimitsu maintains the high level of processing quality by determining overall cutting conditions and realizing the best processing conditions for each individual wafer the customer manufactures. All the dicers have a GUI (Graphical User Interface) as a standard feature, which is used in combination with the auto-alignment function to enable user-friendly operations that reduce manual operations.

AD30TW

- Dicing machine dedicated to large package substrates
  Capable of dicing substrates up to 360 mm x 360 mm in size
- Opposing twin spindle design
  Productivity is improved by minimizing the X axis movement and using two axes simultaneously for processing.
- High-performance, high-power spindle as standard



innovativeCapable of dicing large panels of up to 360 mm by 360 mm



Multiple substrates can be mounted at the same time (250 mm x 75 mm, an example of five substrates on a frame)





AD20T/S

- Space-saving design
  The diagonal layout mechanism reduces footprint by 40% compared to our previous models.
- Semi-automatic dicer with opposing twin spindles or a single spindle capable of handling a 200 mm wide workpiece.
- High-performance, high-power spindle as a standard feature.







SS Series

- High power spindle as standard feature.
- Improved operability with the 17-inch LCD touch panel screen.
- Auto alignment as standard feature.
- World smallest footprint for each machine.



A-CS-300

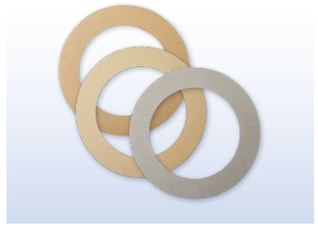
Automated wafer cleaning machine

- Wafer cleaning machine capable of cleaning and drying a 300 mm wide workpiece.
- Optimal for spin cleaning and drying workpieces cut and grooved by a semi-automatic dicing machine or other device.

Semiconductor Production Equipment

Precision ACCRETECH Blades

Through the integration of innovative development and application technologies, ACCRETECH offers a comprehensive lineup of precision dicing blades for a wide range of materials and cutting applications, helping customers achieve both high quality and low cost.



< METAL BOND BLADES >

Metal bond blades based on advanced material technology. A wide product lineup is available. Select the GM series for glass applications and the YM series for ceramic applications.



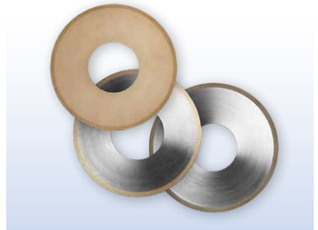
< RESIN BOND BLADES >

Resin bond blades developed for high-speed cutting and long life while maintaining excellent sharpness. Select the PG series for semiconductor packages and the GC series for glass and ceramic applications.



< NICKEL BOND BLADES >

Highly rigid nickel bond blades manufactured by electroforming. They enable thinner blades and longer life than other bond types. They provide excellent cutting accuracy and straightness. Various slit configurations are available for different cutting applications.



< DIAMOND CUTTER >

Cutters with an abrasive grain layer on the outer perimeter of a metal core. They help reduce cost in applications using thick or large-diameter blades with a large amount of abrasive grains.



< ULTRA HARD METAL SAWS >

Ultra-hard metal saws that minimize burrs when cutting resin and metal substrates using cutting edges instead of abrasive grains. We provide optimal solutions for various customer needs.



< DRESSING PLATE / CONDITIONING PLATE >

Dressing plates for maintaining blade quality and cutting performance. Proper dressing under optimized conditions maximizes blade performance.

Semiconductor Production Equipment

Fully Automatic Laser Dicing Machines

Able to perform non-contact dicing without damaging the silicon wafer surface

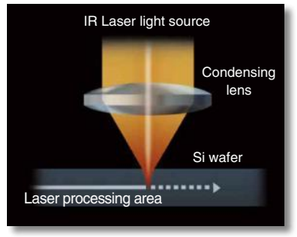


Laser Dicing Machine
ML3200FH

A Ø300 mm laser dicing machine equipped with IR (Infrared) laser. Various loader specifications are available to meet various needs of customers.

【Features】

- Supports completely dry process. Optimum choice for processing devices whose processing load should be minimized and that should be kept away from water.
- Adoption of a high output laser significantly reduced the number of scans required for processing, dramatically increasing the throughput.
- Narrow kerf width increases the yield (number of chips obtained), contributing to cost reduction.



This laser dicing machine removes Low-k film, Cu wiring, TEG, etc. on the street with low damage using UV laser beam.

【Features】

- Ø300mm Compatible fully automatic laser dicing machine
  Automatically supports a series of processes from water-soluble protective film distribution to laser dicing and cleaning.
- Laser Grooving Process compatible
  AL3000 supports applications for removing TEG on Low-k grooves or streets.
- Achieves both high quality processing and high throughput with a unique laser engine mechanism



Laser Dicing Machine
AL3000

Semiconductor Production Equipment

High Rigid Grinders

Realized the damage-free processing in a short amount of time.

Our high rigid grinder is the device to grind hard-to-cut materials such as sapphire and SiC substrates.

HRG300 allows the processing of individual wafers with larger diameters (300 mm) and of the batch grinding of wafers with smaller diameters that are attached to the support substrates.



HRG300

Features

- High-rigidity
- Processing efficiency
- Low processing cost
- Equipped with the batch processing-compliant IPG
- Continuous dressing mechanism (optional)



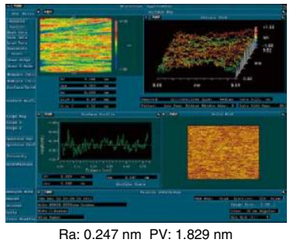
HRG200X

Features

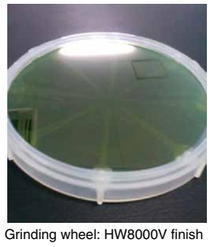
- Fully Automatic High Rigid Twin Axis Grinder
- Less-damage Grinding with Shorter Process Time
- Low processing cost
- High Accuracy
- Mirror Finish Surface Grinding

Processing example of SiC.

Mirror finish becomes available only with grinding.



Ra: 0.247 nm PV: 1.829 nm



Grinding wheel: HW8000V finish

Target material

Hard-to-cut materials such as sapphire, SiC, GaN, ALN, and LT.

Target work

Size: ϕ 2 ～ ϕ 12 inch
Max. thickness: 20 mm
(including the thickness of the support substrate)

Semiconductor Production Equipment

High Rigid Grinders

Pursuing the limit of grinding machines.

ACCRETECH High Rigid Grinders enable mirror finishing with no use of chemicals and contribute to achieving high precision, high throughput and low cost in the wafer thinning process.



HRG3000RMⅡ

Features

- Fully Automatic High Rigid Twin Axis Grinder
- Less-damage Grinding with Shorter Process Time
- Low processing cost
- High Accuracy
- Mirror Finish Surface Grinding

Grinder for Front-End Processing

Delivering high-rigidity grinding accuracy to front-end processes. Simultaneously achieving high flatness accuracy, high cleanability, and high throughput, this grinder contributes to advanced 3D integration and packaging processes.



HRG3000XF

Features

- Front-end level high-flatness processing accuracy
- Front-end level high cleanability
- Further enhanced throughput

Semiconductor Production Equipment

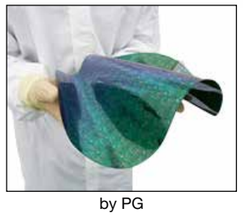
Polish Grinders

Inspired by Tokyo Seimitsu's own innovative engineering, this polish grinder offers an integrated solution for thinner wafers and damage removal required for system-in-package products, and 3D mounting technology while eliminating wafer damage during transport.



Features

- Integrated operation : Handles rough and fine grinding, polishing, and wafer cleaning on both sides in a single unit
- Safety measures : All manufacturing processes are completed in a wet state, preventing the release of fine particles
- Stable wafer transfer : Ground wafers are transported throughout all processes with minimum handling
- The equipment offers integrated data control and communication systems : the RM module combines a transport mechanism for minimal transfer of thin wafers with an inline connection system ; measurement is performed by a post-process gage.
- Quality management: Data management and Communication using Post process gauge



by PG



by HRG

Target material

Si, SiC, Glass, Mold package etc..

Target work

Size: ϕ 8 ～ ϕ 12 inch
Minimum finish thickness: 10 µm

Semiconductor Production Equipment

Chemical Mechanical Planarizers

Integrating the technologies of precision measuring machines and semiconductor manufacturing systems developed thus far, Tokyo Seimitsu offers the ChaMP series Chemical Mechanical Planarizers that meet diverse process requirements.
(Applicable wafer sizes: 300mm, 200mm, 150mm, 100mm)

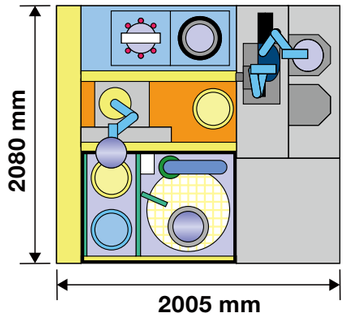
Compact High-Performance CMP

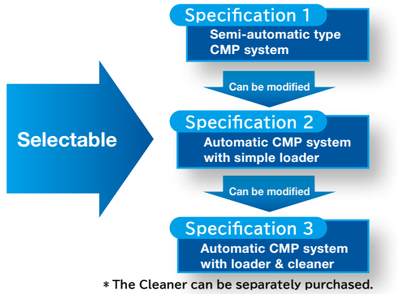
ChaMP211



Feature

- Low price, small foot print
- High-performance CMP:
  Developed technology through the mass production line of the semiconductor device.
- Flexible customization meeting user's needs
  --->Expendable from R&D, trial, to mass production.





* The Cleaner can be separately purchased.

Standard Model

ChaMP232

For 200 mm or 150 mm or 100 mm wafers

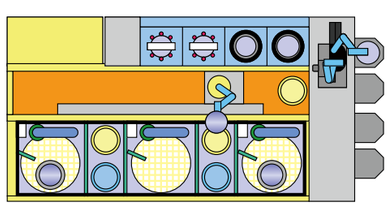
ChaMP332

For 300 mm wafers

Feature

- Supports all types of application with a 3 platen, 2 head configuration
- All machines supporting 300mm/200 mm/150 mm/100 mm wafers are equipped with similarly conceived polishing heads and EPD system.



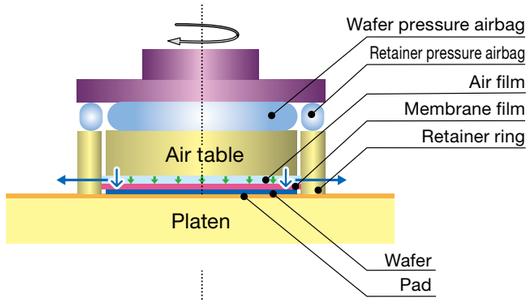


Air-float head enables low-pressure and high planarity process “Sylphide”

- Extremely uniform pressure distribution by air film above wafer.
- Stable pressure control at low pressures made possible with airbags independent from air films.
- Independent retainer pressure airbags enable better edge profile control.
- Unique design of retainer/membrane assembly reduces machine downtime. (Refer to below.)
- Zone control function is optionally possible.

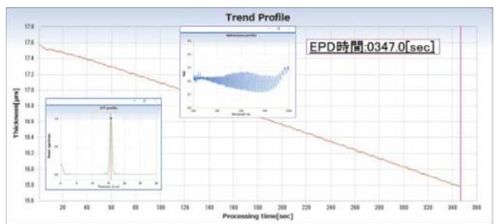
CMP's outstanding head work not only improves the process performance but also increases the productivity as well as reduces costs. More precisely, adapting the well refined hard pats can shorten the polishing time and thus reduce the cost of consumables.

Sylphide

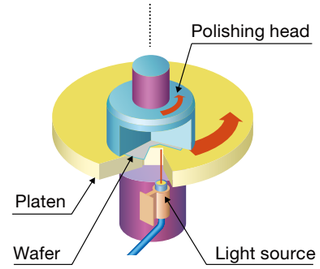


Optical End-Point Detection System

- Uses white light source and accurately detects residual film changes with reflection data of wide wavelength range and original algorithm.
- Provides a wide range of applications.
- Equipped with intuitive GUI that allows the user to see film thickness changes.



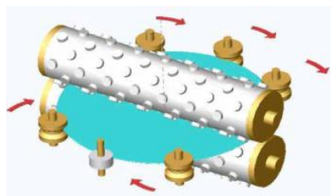
EPD detection mechanism



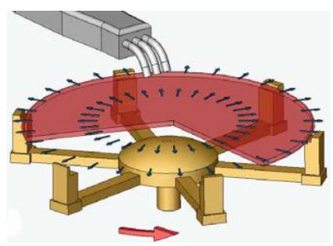
Cleaning machine

- Enables cleaning of 300 mm / 200 mm / 150 mm / 100 mm wafers and flexibly handles square or other special substrates.
- Achieves cleaning suitable for state-of-the-art processes.
- Enables simultaneous cleaning of front and back surfaces.

Scrub cleaning



Spin-drying



Semiconductor Production Equipment

Wafer Manufacturing Systems

As the leading supplier of silicon wafer manufacturing equipment, our acclaimed engineering has succeeded in systemizing the wafer manufacturing process.

As the semiconductor devices get smaller in size,demand for precision machining technology for silicon wafers increases. Tokyo Seimitsu provides a line of wafer manufacturing systems respectively designed for individual processes such as sliced wafer demounting and cleaning, wafer edge grinding, and more to ultimately improve product quality and productivity. We offer consultations to select the optimal systems for automation and process management as well as providing technical and maintenance support going forward. Our core products, Wafer Edge Grinding Machine for 300 mm wafers and Demounting and Cleaning Systems for sliced carbon wafers are highly evaluated by customers and have secured the world-class market share.

Wafer Edge Grinding Machine W-GM Series

- Newly-developed grinding unit enhances the rotative precision of the spindle, and improves the edge roughness.
- Non-contact measuring system achieves stable alignment.
- Multiple-point of thickness of pre-processed wafers , diameter and notch depth of post-processed wafer are measured by non-contact system.
- Options such as low damage grinding to reduce machining damage are available.



W-GM-6200

- Wafer Size ϕ 450 mm.
- Improve the Space Efficiency by the Compact Design.
- Highly Accurate Grinding by the Synchronized X, Y, θ Support Control.
- Easy Operation by Touch Panel.



W-GM-5200E

- Machine specification ready for 300 mm (ϕ 12″) wafers.
- Makes possible high precision and high quality 300 mm wafer processing.
- Newly-developed built-in inspection system (option) enables real-time monitoring inside the machine of wafers quality control after grinding.



W-GM-4200E

- Machine specification ready for 50 mm (ϕ 2″) - 200 mm (ϕ 8″) wafers.
- Newly-developed grinding unit enhances the rotative precision of the spindle, and improves the surface roughness.
- Performs non-contact measuring of pre-processed wafer thickness, diameter and notch depth of post-processed wafer.

W-GM-4200S

- Workpieces in various shapes (rectangular and polygoral shapes) can be processed.

Demounting and Cleaning System (C-RW-200 / 300)

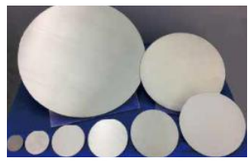
- Automatic demounting of wafers from the slicing base,cleaning and storing on the cassette.



Grinding Service

Our edge grinding machines can be used for various applications and with various materials such as Si, SiC, GaN, sapphire, compounds and oxidized materials.
We will provide you with the machining technology we have accumulated.

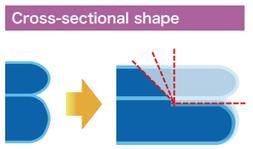
Process Example *Edge Roughness (Ra = 20 nm) *Measured by Our Standard



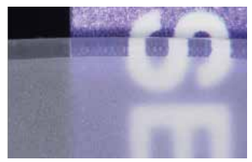
Si Wafer 2" (50 mm) ～ 18" (450 mm)



Terrace Grinding
Counter Measure against Knife Edge/Asymmetric Profile Grinding



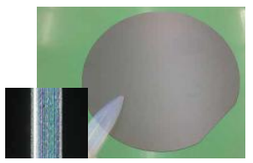
Edge Trimming
Bonded Wafer with Special Profile



Edge grinding of the mirror finished surface of sapphire wafer



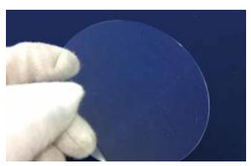
Notch grinding of SiC, sapphire, and brittle materials



Compound Materials such as SiC & GaN



Ingot Rounding
Maximum Thickness: 30 mm



Glass Wafer Edge Grinding



Square / Rectangle Glass Substrate

How We See CSR

Tokyo Seimitsu Group does business activities based on its corporate philosophy, “Growing together with partners and customers by collaborating technology, knowledge, and information to create the world’s No.1 products.” Throughout these activities, we create WIN-WIN relationships between all the stakeholders such as shareholders, suppliers, employees, local community, international society, actively play an important role on the realization of a sustainable society, and make efforts to enhance our corporate value.

Motto

WIN-WIN RELATIONSHIPS CREATE THE WORLD’S NO.1 PRODUCTS!























Corporate Philosophy

We create the world's No. 1 products and grow together to a higher level by integrating excellent technology, wisdom and information available in the world.

Based on our corporate philosophy, Tokyo Seimitsu Group has contributed to the enhancement of convenience in society and the reduction of environment impact through providing precision measuring instruments and semiconductor manufacturing equipment that are vital for our customers’ manufacturing process and energy- and resource-saving products.This means that the measuring technologies and products that Tokyo Seimitsu Group provides support manufacturing activities of customers and that end products produced through those activities support the entire society.
In recent years, while the environment that surrounds companies changes significantly, Tokyo Seimitsu Group rec+ognizes that sustainability is one of our most important business issues and continues to promote sustainability activities more than ever.To achieve the sustainable growth for our group and society, we have set Purpose (raison d’être) as “Gaging the future with Metrology, Creating the future with Semiconductors.”Using this as a starting point, we will further enhance the effectiveness of our sustainability activities by defining material issues and reflecting specific initiatives and targets in the Mid-term Management Plan. In addition, we will strengthen our sustainability promotion structure to realize our Purpose and aim to realize a sustainable society and the sustainable growth of Tokyo Seimitsu Group through dialogue and collaboration with our stakeholders.

Outline of Company

Name

TOKYO SEIMITSU CO., LTD.

Establishment

March 28, 1949

Capital

Paid-in capital : 11,748 million yen
(as of March 31, 2026)

Stocks

Listed on the Prime Market of the Tokyo Stock Exchange

Employees

Non-consolidated : 1,428
Consolidated : 2,890
(as of March 31, 2026)

Directors and Auditors

Hitoshi YOSHIDA	Chairman
Ryuichi KIMURA	President and CEO
Takahiro HOKIDA	Director
Romi PRADHAN	Director
Kiyoshi TAKAMASU	External Director
Kazuya MORI	External Director
Shinji AKIMOTO	Director (Serving as Audit and Supervisory Committee Members)
Yuriko SAGARA	External Director (Serving as Audit and Supervisory Committee Members)
Motoko KAWASAKI	External Director (Serving as Audit and Supervisory Committee Members)
Sumiko TAKAYAMA	External Director (Serving as Audit and Supervisory Committee Members)

(as of June 22, 2026)

Affiliates

Tosei Engineering Corp.
Tosei Systems Co., Ltd.
Accretech Create Corp.
Tosei Box Corp.
Accretech Finance Co., Ltd.
Accretech America Inc.
Accretech (Europe) GmbH
Accretech Korea Co., Ltd.
Accretech (China) Co., Ltd.
Accretech Taiwan Co., Ltd.
Accretech (Malaysia) Sdn. Bhd.
Accretech (Thailand) Co., Ltd.
Accretech Adamas (Thailand) Co., Ltd.
Tosei Engineering (Pinghu) Co., Ltd.
TOSEI (Thailand) Co., Ltd.
Accretech SBS Inc.
Accretech (Singapore) Pte. Ltd.
Accretech Vietnam Co., Ltd.
PT Accretech Indonesia
Accretech-Tosei do Brasil Ltda.
PT TOSEI Indonesia.
TOSEI Philippines Corp.
TOSEI Engineering Pvt. Ltd.
TOSEI Mexico, S.A. de C.V.
Accretech SBS UK Ltd.
Accretech-Tosei Hungary Kft.
Accretech (Pinghu) Co., Ltd.

In-house Company System and Executive Officer System

Semiconductor Company

Takahiro HOKIDA	Head of Semiconductor Company
Yuichi KUBO	Managing Executive Officer
Masaki KANAZAWA	Managing Executive Officer
Ryoichi IDE	Managing Executive Officer
Hiroyuki SAKAI	Managing Executive Officer
Romi PRADHAN	Executive Officer
Keng Hooi TEE	Executive Officer
Koji AKADA	Executive Officer
Ryo SAKATA	Executive Officer

Metrology Company

Kazumasa ISHIKAWA	Head of Metrology Company
Taichi FUJITA	Managing Executive Officer
Takashi MASUDA	Executive Officer
Mutsumi ONO	Executive Officer
Tetsuya KIKUTA	Executive Officer
Yoichi TOGAWA	Executive Officer
Hikaru MASUTA	Executive Officer

Administration Company

Asashi KATO	Head of Administration Company
Kimito KOIZUMI	Managing Executive Officer
Tomoko INOSE	Executive Officer

Brief History

- 1949 •Establishment of Tokyo Seimitsu Kogu Co., Ltd.
- 1951 •Manufacture and sale of measuring machines using mechanical gages
- 1952 •Development of Japan's first flow type air micrometer
- 1957 •Development of Japan's first LVDT type electric micrometer
  •Establishment of Daiichi Seiki Co., Ltd.
- 1958 •Development of germanium pellet auto-sorter
- 1962 •Company name changed to Tokyo Seimitsu Co.,Ltd.
  •Listed on the second section of the Tokyo Stock Exchange
  •Development of surface texture measuring instrument
- 1963 •Development of Japan's first wafer slicing machine
- 1964 •Development of wafer probing machine
- 1967 •Development of roundness measuring instrument
- 1969 •Establishment of Tosei Engineering Service Co.,Ltd.
  •Development of Japan's first coordinate measuring machine
- 1970 •Development of the wafer dicing machine
- 1985 •Establishment of Tosei Systems Co., Ltd. as a software development group
- 1986 •Listed on the first section of the Tokyo Stock Exchange
- 1987 •Establishment of Research Laboratory
- 1989 •Establishment of Tokyo Seimitsu Europe GmbH (Germany) and Tokyo Seimitsu America, Inc.(USA)
- 1992 •Establishment of ACCRETECH Service Center in Korea
- 1994 •ISO 9001 awarded to the Hachioji and Tsuchiura Plants
  •Obtained a business license under the traceability system of the Measurement Law for the calibration of the "length measurement laser"
  •Establishment of the Beijing Representative Office
  •Establishment of Tokyo Seimitsu (Malaysia) Sdn.Bhd. in Malaysia
- 1995 •Obtained a business license under the traceability system of the Measurement Law for the calibration of the "Block gage"
  •Establishment of ACCRETECH America, Inc. and ACCRETECH Manufacturing Company in USA
  •Entered into a partnership with Carl Zeiss in the field of high precision measuring instruments worldwide
- 1996 •Received the "10 BEST Award" for "Customer satisfaction with a semiconductor equipment supplier" survey by VLSI Research Inc.
  •Establishment of the TSK Technical Center in Hsinchu, Taiwan
- 1997 •Establishment of Tokyo Seimitsu (Singapore) Pte.Ltd.
- 1998 •ISO 14001 awarded to the Hachioji and Tsuchiura Plants
- 1999 •Establishment of ACCRETECH Finance Co., Ltd.
- 2001 •Corporate brand "ACCRETECH" introduced
  •Establishment of Tosei Box Corp.
- 2002 •Received the "10 Best Award" in two categories : awarded for the 7 consecutive years in the Test & Material Handling Equipmentcategory, and the awarded in the Assemby Equipment category for the first time
  •Establishment of Accretech (China) Co.,Ltd.
  •Entered into a partnership with Hamamatsu Photonics K.K. for developing semiconductor manufacturing equipment and jointly developed a new laser dicing system, "MAHOHDICING MACHINE"
- 2005 •Renewed partnership agreement with Carl Zeiss for another 5 years
- 2007 •Establishment of Accretech Korea Co.,Ltd.
  •MAHOHDICING MACHINE was granted the Chairman' Award of The Japan Machinery Federation at its 27th JMF Award for Energy-Conserving Machinery.
  •Obtained a business license at Tsuchiura Plant under the traceability system of the Measurement Law for the calibration of the "length measurement laser" and "3D Coordinate Measuring Machine"
- 2008 •Received the "10 BEST Awards" in two categories :awarded for 13 consecutive years in the Test & Material Handing Equipment category, and for 7 consecutive years in the Assembly Equipment category
  •Technical cooperation with Mitaka Kohki Co., Ltd in non-contact metrology
- 2009 •Establishment of Accretech America Inc.
- 2010 •Relocation the head office to Hachioji City
- 2011 •Completed the No. 5 Plant at Hachioji Semiconductor company
- 2012 •Acceptance of Dicing Blade Business from Mitsubishi Material Corporation and started Blade Business
  •Established "ACCRETECH Application Center" accommodating to device process diversification
- 2015 •Changed company name of Tokyo seimitsu (Thailand) Co., Ltd. to Accretech (Thailand) Co., Ltd.
- 2016 •Completed the No. 6 Plant at Hachioji Semiconductor company.
- 2017 •Joint Development with Panasonic Factory Solutions Co., Ltd. to promote Laser Grooving Device used in Plasma Dicing method.
- 2019 •Establishment of Accretech Powertro System Co.,Ltd.
  •Establishment of Accretech SBS Inc.
  •Establishment of Accretech SBS UK Ltd.
- 2020 •Construction of Tsuchiura Plant MI Building completed
  •Semiconductor Business Department office opened at the subsidiary in Vietnam
  •Acquisition of 100% ownership of Accretech Powertro System Co., Ltd. (former Fujitsu Telecom Networks Fukushima Ltd.) completed
- 2021 •Construction of new building for Tokyo Seimitsu subsidiary Accretech Taiwan Co., Ltd was completed
  •New Taiwan Application Center was opened
- 2022 •Due to the revision of the market classification of the Tokyo Stock Exchange, the Company moved to the Prime Segment
- 2023 •Construction of Hanno plant of Semiconductor Company was completed
  •Transfer of development, manufacturing, and sales business of charge/discharge testing system from a consolidated subsidiary, Accretech Powertro System Co., Ltd.
- 2025 •Construction of Nagoya plant was completed

Tokyo Seimitsu Co., Ltd. Head Office/Plant



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Tosei Engineering Corp. Head Office/Plant

*Tosei Engineering is a group company of Tokyo Seimitsu and manufactures semiconductor manufacturing equipment and automatic measuring instruments.



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Nagoya Plant
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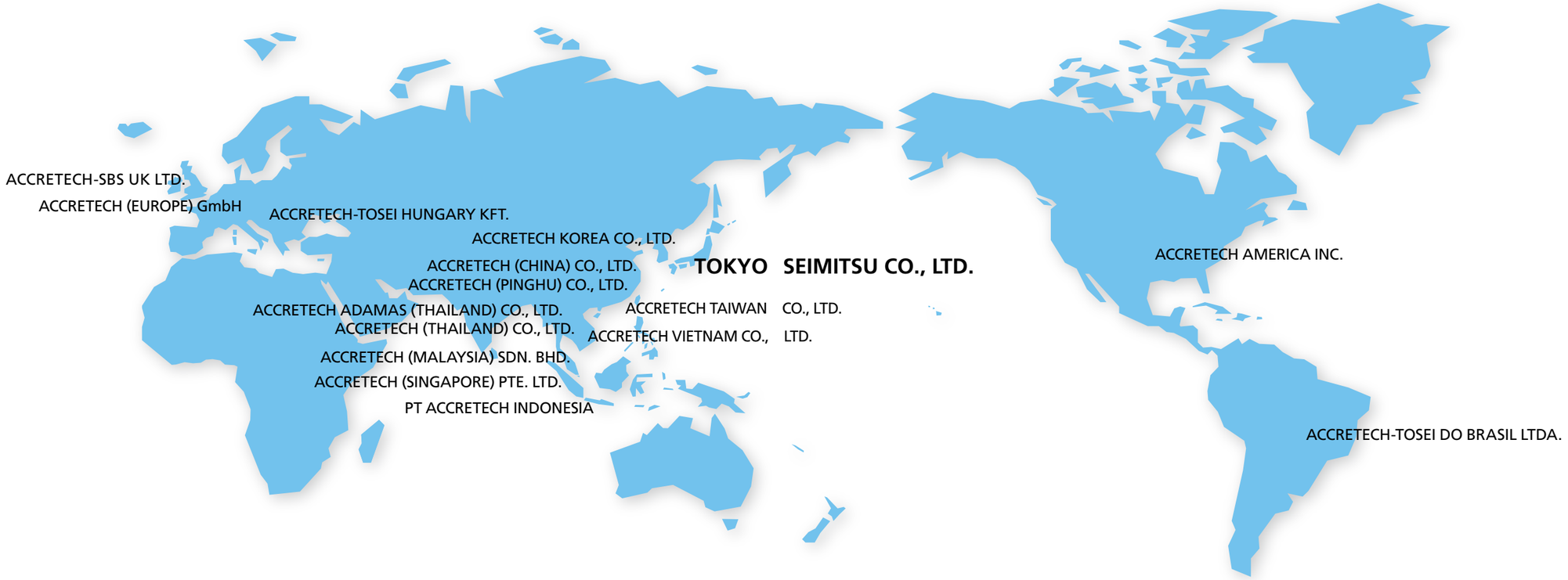

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